

PATENT ASSIGNMENT

Electronic Version v1.1

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SUBMISSION TYPE:

NEW ASSIGNMENT

NATURE OF CONVEYANCE:

ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Satoru Yukie	01/05/2004
Mike Kwon	01/05/2004
Duk San Kim	01/05/2004
Craig M. Hagopian	01/05/2004

RECEIVING PARTY DATA

Name:	Axesstel, Inc.
Street Address:	6815 Flanders Drive
Internal Address:	Suite 210
City:	San Diego
State/Country:	CALIFORNIA
Postal Code:	92121

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	11530214

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:

113750-2003C1

NAME OF SUBMITTER:

Samuel S. Lee

PATENT

500163894

REEL: 018383 FRAME: 0604

CH \$40.00 11530214

Total Attachments: 2  
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**ASSIGNMENT**

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in ENHANCED MOBILITY WIRELESS LOCAL LOOP PHONE for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, AXESSTEL INC., a California corporation, with offices at 6305 Lusk Boulevard, San Diego, California 92121 (hereinafter referred to as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, for good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the application number and filing date of this application in the spaces that follow: Application Number: 10/660,080, Filing Date: September 10, 2003.

This assignment executed on the dates indicated below.

Satoru Yukie  
Name of first or sole inventor

1-5-04  
Execution date of U.S. Patent Application

San Diego, CA  
Residence of first or sole inventor

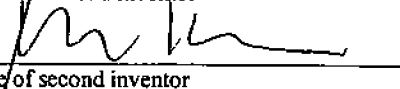
  
Signature of first or sole inventor

1-5-04  
Date of Assignment

Mike Kwon  
Name of second inventor

JANUARY 5, 2004  
Execution date of U.S. Patent Application

San Diego, CA  
Residence of second inventor

  
Signature of second inventor

JANUARY 5, 2004  
Date of Assignment

Duk San Kim  
Name of third inventor

1-5-04  
Execution date of U.S. Patent Application

San Diego, CA  
Residence of third inventor

  
Signature of third inventor

1-5-04  
Date of Assignment

Craig M. Hagopian  
Name of fourth inventor

JAN 5, 2004  
Execution date of U.S. Patent Application

San Diego, CA  
Residence of fourth inventor

  
Signature of fourth inventor

JAN 5, 2004  
Date of Assignment